

## OE-A Members – Companies



- A** Adhesives Research Ireland (IE)  
A.F. Suter (GB)  
Adphos Digital Printing (DE)  
Adphos North America (US)  
Apeva (DE)  
Alpha Assembly Solutions (US)  
Altana (DE)  
American Semiconductor (US)  
Argus Albion (RU)  
Arjowiggins Creative Papers (FR)  
ARM Ltd. (GB)  
Armor (FR)
- B** BASF Coatings Schweiz (CH)  
BASF New Business (DE)  
Beneq Oy (FI)  
Bosch Rexroth (DE)  
Brewer Science (US)  
Brückner Maschinenbau (DE)  
BST Eltromat International (DE)
- C** Cambrios Advanced Materials (US)  
CDT Cambridge Display Technology (GB)  
Ceradrop (FR)  
Coatema Coating Machinery (DE)  
CondAlign (NO)  
Continental Automotive (DE)  
Coruna Printed Electronics (CH)  
Cynora (DE)
- D** db-matik (DE)  
Dowa HD Europe (DE)  
Dracula Technologies (FR)  
DuPont Advanced Materials (GB)  
DuPont Teijin Films (GB)  
Dymco (JP)
- E** Edvard Schneider (SE)  
Elantas Europe (DE)  
Elmeric (DE)  
Emde development of light (DE)  
Enfucell Flexible Electronics (CN)  
Engineered Materials Systems (US)  
EppsteinFolios (DE)  
Eptatech (IT)  
Erhardt+Leimer (DE)  
Ersa (DE)  
Evonik Creavis (DE)  
Exakt Advanced Technologies (DE)
- F** Felix Böttcher (DE)  
FlexEnable (GB)  
Folex Coating (DE)  
FUELIUM (ES)  
Fujifilm Dimatix (US)
- G** Genes'Ink (FR)  
Giesecke & Devrient (DE)  
Greiner Technology & Innovation (AT)  
GRT (DE)  
GT+W (DE)  
Guangdong Juhua Printing (CN)
- H** Haydale Technologies Thailand (TH)  
Heliatek (DE)  
Heraeus Deutschland (DE)  
Hoffmann + Krippner (DE)
- I** IBS Precision Engineering (NL)  
IEE (LU)  
InkTec (DE)  
InnovationLab (DE)  
InovisCoat (DE)  
Inotec Barcode Security (DE)  
Is it fresh (DE)  
ISORG (FR)
- J** JT International Germany (DE)
- K** Karl Knauer (DE)  
Kateeva (US)  
Kelenn Technology (FR)  
Kroenert (DE)  
KSG (DE)
- L** LG Technology Center Europe (DE)  
Liquid X Printed Metals (US)  
Lohmann (DE)
- M** M. Braun Inertgas-Systeme (DE)  
MMP Premium Printing Center (DE)  
M-Solv (GB)  
Masar Printing and Publishing (AE)  
Matti Technology (CH)  
Merck (DE)  
MSW (DE)
- N** NeuDrive (GB)  
New Cable Corporation (FI)  
NovaCentrix (US)  
Novaled (DE)  
nsm Norbert Schläfli (CH)  
NXT (DE)
- O** OLEDWorks (DE)  
Organic Electronic Technologies (GR)  
Osram Opto Semiconductors (DE)  
Oxford Photovoltaics (GB)
- P** PCAS (FR)  
Piezotech (FR)  
Plastic Logic (DE)  
Policrom Screens (IT)  
PolyIC (DE)  
PragmatIC Printing (GB)  
Printcolor Deutschland (DE)  
Printed Electronics (GB)  
Pütz Folien (DE)
- Q** Quantumatica (IT)
- R** Raynergy Tek (TW)  
Reisewitz Beschichtungen (DE)  
RK Siebdrucktechnik (DE)  
ROWO Coating (DE)
- S** SABIC (NL)  
SAES Getters (IT)  
SAIT Europe (GB)  
Saueressig (DE)  
Senorics (DE)  
Schoeller Technocell (DE)  
Schreiner Group (DE)  
SmartKem (UK)  
Smit Thermal Solutions (NL)  
Smooth & Sharp Corporation (TW)  
SunaTech (CN)  
Surteco (DE)
- T** Teknek (GB)  
Temicon (DE)  
Thin Film Electronics (NO)  
Toppan Europe (DE)  
Toyobo (JP)  
TSE Troller (CH)
- V** VARTA Microbattery (DE)  
VDL Flow (NL)  
VFP Ink Technologies (FR)
- W** Werner Blase (DE)  
Witte plusprint (DE)
- X** X-Celeprint (IE)  
Xenon Corporation (US)  
Xiamen Funano New Material (CN)  
Xymox Technologies (US)
- Y** Ynvisible (PT)  
YTC America (US)
- Z** ZEON (JP)

## OE-A Members – Universities / Institutes



- A** AIST - Flexible Electronics Research Center (JP)  
AIT – Austrian Institute of Technology (AT)  
Aristotle University of Thessaloniki - LTFN (GR)
- B** Bauhaus-Universität Weimar (DE)  
BRNO University of Technology (CZ)
- C** CEA Liten (FR)  
Centi - Centre for Nanotechnology & Smart Materials (PT)  
COPT Center (DE)  
CPI - Centre for Process Innovation (GB)  
CSEM (CH)  
CSEM Brasil (BR)  
CSIR (ZA)  
CSIRO (AU)
- E** EMPA (CH)  
Eurecat (ES)
- F** Fontys University of Applied Sciences (NL)  
Fraunhofer ENAS (DE)  
Fraunhofer FEP (DE)  
Fraunhofer IAP (DE)  
Fraunhofer IFAM (DE)  
Fraunhofer ILT (DE)  
Fraunhofer IPA (DE)  
Fraunhofer ISC (DE)  
Fraunhofer POLO (DE)  
Friedrich-Alexander-Universität – WW6 – i-Meet (DE)  
Friedrich Schiller Universität Jena (DE)
- G** Georgia Tech – Center for Organic Photonics and Electronics (US)
- H** Hahn-Schickard – Institut für Mikroaufbautechnik (DE)  
Hochschule der Medien - IAF, IAD (DE)  
Hochschule Niederrhein (DE)  
Holst Centre (NL)
- I** ICI – Printability and Graphic Communications Institute (CA)  
IK4-CIDETEC (ES)  
IMB-CNM (CSIC) (ES)  
Imec (BE)  
Imperial College London – Centre for Plastic Electronics (GB)  
Insitut für Mikroelektronik Stuttgart (DE)  
INM - Leibniz Institut für Neue Materialien (DE)  
Instytut Technologii Elektronowej (PL)  
IPC – Technical Centre of Plastics Engineering (FR)
- ITRI - Industrial Technology Research Institute (TW)
- J** Joanneum Research (AT)  
Johannes Kepler Universität Linz - LIOS (AT)
- K** Karlsruhe Institute of Technology - LTI (DE)  
Konkuk University - FDRC (KR)
- L** Landshut University of Applied Sciences (DE)  
Leitat Technological Center (ES)  
Loughborough University (GB)
- M** MINES Saint-Étienne – Microelectronics - Center of Provence (FR)  
Munich University of Applied Sciences – Print and Media Technologies (DE)
- N** National Research Council Canada (CA)  
NPL - National Physics Laboratory (GB)
- O** Oulu University of Applied Sciences (FI)
- P** Palo Alto Research Center (US)  
Profactor (AT)
- R** RISE Acreo (SE)  
RWTH Aachen University - ITA (DE)
- S** Singapore Institute of Manufacturing Technology (SG)  
Sunchon National University (KR)  
Suzhou Institute of Nanotech - PERC (CN)
- T** Tampere University (FI)  
Technische Hochschule Köln (DE)  
Technische Hochschule Nürnberg Georg Simon Ohm (DE)  
Technische Universität Chemnitz (DE)  
Technische Universität Darmstadt - IDD (DE)  
Technische Universität Dresden - IAPP (DE)  
TOPIC – Thailand Organic and Printed Electronic Innovation Center (TH)
- U** University of Applied Sciences Northwestern Switzerland (CH)  
University of West Bohemia – RICE (CZ)  
University of Bordeaux (FR)  
University of Cagliari (IT)  
University of Cambridge – Electrical Engineering Division (GB)  
University of Leeds – Digital Print (GB)  
University of Manchester (GB)
- University of Novi Sad – Faculty of Technical Sciences (CS)  
University of Oulu (FI)  
University of Pardubice (CZ)  
University of St. Andrews – Organic Semiconductor Centre (GB)
- V** VTT - Technical Research Centre of Finland (FI)
- W** WCPC - Swansea University (GB)
- Y** Yamagata University (JP)